

3DIT-MSP&DL2021

The 3rd International Conference on 3D Imaging

Technologies-Multidimensional Signal Processing and Deep Learning

(3DIT-MSP&DL 2021)

Invitation Letter

November 26-28, 2021, Kunming, Yunnan, China

Dear _Author_

The 3rd International Conference on 3D Imaging Technologies-Multidimensional Signal Processing and Deep Learning(3DIT-MSP&DL 2021) will be held during November 26-28, 2021 in Kunming, Yunnan, China. In view of your outstanding contributions in this field, we sincerely invite you to attend our conference.

The 3DIT-MSP&DL2021 aims to provide a forum that brings together researchers and academia as well as practitioners from industry to meet and exchange their ideas and recent research development work on all aspects of Images and Multidimensional Signal Processing, their applications and other related areas. The focus of the conference is to establish an effective platform for institutions and industries to share ideas and to present the works of scientists, engineers, educators and students from all over the world. The organizing committee of conference is pleased to invite prospective authors to submit their original manuscripts to 3DIT-MSP&DL2021.

The key to success of our conference is to get your support. We will appreciate if you can attend our conference.

Communication Method: Oral Presentation or Poster Exhibition

Organizer: Yunnan Normal University

SIKSHA 'O' ANUSANDHAN

IRNet International Academic Communication Center

3DIT-MSP&DL2021 Conference Committee authorizes Wuhan Hualianpobo Culture Communication Co., Ltd. to draw up invoice and deal with payment.

The invoice charge of 3DIT-MSP&DL2021 Conference Committee includes publication fee, conference materials. Author themselves should pay accommodation, meals and transportation fee.

3DIT-MSP&DL2021 Conference Committee



3DIT-MSP&DL2021

第三届三维成像技术-多维信号处理与深度学习国际会议

(3DIT-MSP&DL2021)

邀请函

2021年11月26-28日，昆明，中国

尊敬的__作者__

第二届三维成像技术-多维信号处理与深度学习国际会议(3DIT-MSP&DL2020)将于2021年11月26-28日在中国，昆明举办。鉴于您在三维图像技术，多维信号处理及相关领域的突出贡献，3DIT-MSP&DL会务组真挚的邀请您参加并出席本次大会，您的热情支持是大会取得圆满成功的重要前提，特此感谢您的莅临。

一、会议主题：

The 3rd International Conference on 3D Imaging Technologies-Multidimensional Signal Processing and Deep Learning (3DIT-MSP&DL 2021)

二、报到地点：

Fontaine Blanche Hotel 云南丽水云泉大酒店

酒店地址：云南省昆明市呈贡区大学城聚贤街768号(云南师范大学呈贡校区内)

三、交流方式：

口头报告&海报展示

四、主办方

云南师范大学

SIKSHA 'O' ANUSANDHAN

IRNet 国际学术交流中心

3DIT-MSP&DL 2021 会务组委托武汉华联帕博文化传播有限公司代为收款并开具发票以及安排相应的会务活动。参会期间的差旅和食宿由参会作者自行承担。



3DIT-MSP&DL2021 组委会

